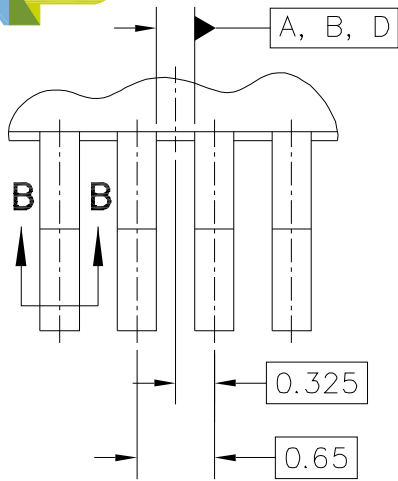
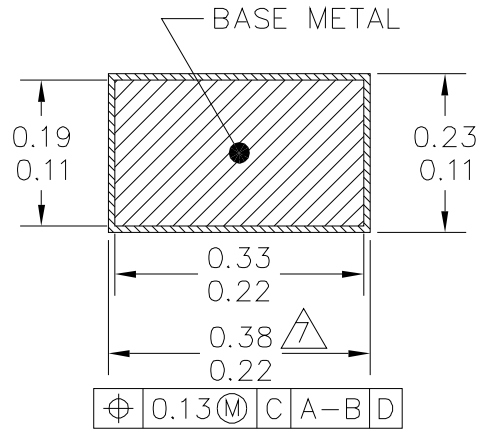


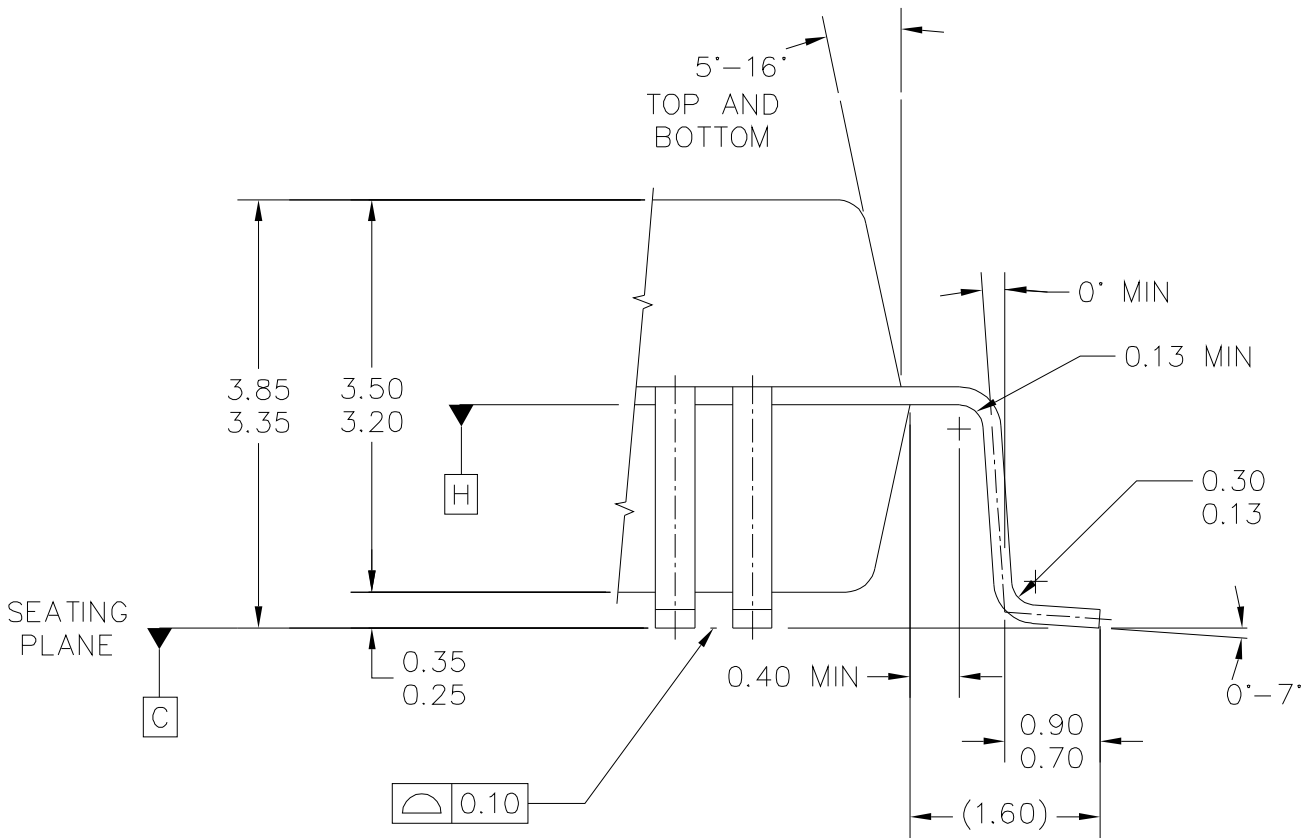
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TITLE: QUAD FLAT PACKAGE (QFP) 160 LEAD, 0.65 PITCH (28.00 X 28.00 X 3.30 PKG)	DOCUMENT NO: 98ASB42810B	REV: F
	STANDARD: NON-JEDEC	
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DETAIL A



SECTION B-B



DETAIL C

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NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

2. CONTROLLING DIMENSION: MILLIMETER.

3. DATUM PLANE IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.

4. DATUMS TO BE DETERMINED AT DATUM PLANE H.

5. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.

6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.

7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

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